



Evaluate CMP for Conductive Layer Thickness

Lei 1500 Family for Non-Contact, Non-Destructive High Throughput Mapping and Uniformity Copper and Barrier Layers

LEI'S 1500 Family provides effective characterization of your CMP Process performance for conductive layers such as copper and copper barrier layers. With our Non-Contact, Non-Destructive 1500 systems you can optimize CMP processing and perform process control to keep operations on target and within budget. Mapping of layer thickness values determines film uniformity based on material resistivity. Significant limitations of 4 point probes are avoided.

Comparison of

LEI Non-Contact-Non Destructive

vs

Four Point Probe

- No Probe Qualification
- No Probe damage or replacement
- Not affected by native surface oxides
- No thin film damage with repeated measurement
- No cross contamination
- Measurement precision consistently better than best qualified four point probe results.

- Probe Qualification Required
- Probe damage is progressive may be rapid and requires replacement
- Probe may not penetrate native oxide may be caused by probe contamination
- Each probe cycle causes progressive thin film damage
- Probing different materials or contaminated materials can transfer the materials or contamination
- Acceptable precision requires probe qualification and monitoring

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